

date 08/05/2022

page 1 of 3

SERIES: HSE02 | DESCRIPTION: HEAT SINK

FEATURES

- extruded design
- · thermal pad option
- aluminum alloy





MODEL		thermal resistance ¹				
	thermal pad	@ 75°C ∆T, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ∆T, nat conv (W)
HSE02-173213	no	21.44	26.1	6.7	4.2	3.50
HSE02-173213P	yes	21.44	26.1	6.7	4.2	3.50

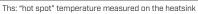
Note: 1. See performance curves for full thermal resistance details.

THERMAL PAD SPECIFICATIONS

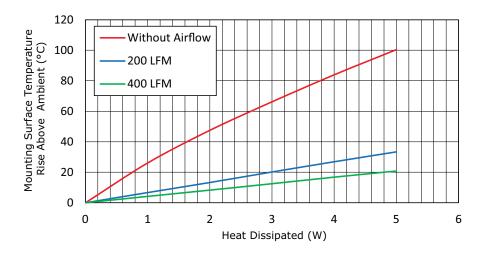
min typ	max	units
0.2		mm
1.9		
300		kV
0.7		W/m*K
1.82		cm²*K/W
-		0.7

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)			
Power (W)	Natural Conv.	200 LFM	400 LFM	
0	0	0	0	
1	26.1	6.7	4.2	
2	47.5	13.3	8.3	
3	66.2	20.2	12.5	
4	83.9	26.9	16.8	
5	100.4	33.4	20.8	



Ta: ambient temperature

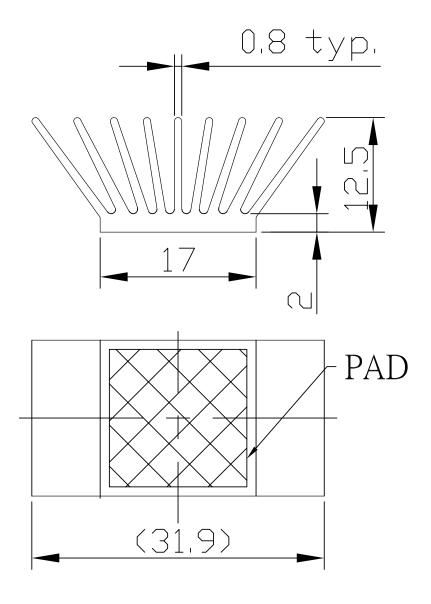


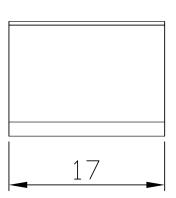
MECHANICAL DRAWING

units: mm

tolerance: ±0.5 mm

MATERIAL	AL 6063-T5
FINISH	blue anodized
WEIGHT	6.9 g





REVISION HISTORY

rev.	description	date
1.0	initial release	04/20/2022
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



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